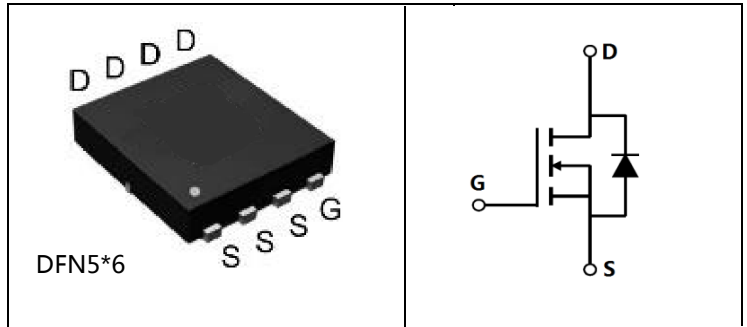


## Features

- $BV_{DSS} = 80V$ ,  $I_D = 130A$
- $R_{DS(on)} : 2.6m\Omega$  (typ) @  $V_{GS} = 10V$
- N-Channel
- Extremely low switching loss
- Excellent stability and uniformity
- 100% Avalanche test



Device Marking and Package Information		
Ordering code	Package	Marking
MPGJ80R040	DFN5*6	MPGJ80R040

## Maximum ratings, at $T_A = 25^\circ C$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	80	V	
$V_{GS}$	Gate-Source voltage	$\pm 20$	V	
$I_S$	Diode continuous forward current	$T_C = 25^\circ C$	130	A
$I_D$	Continuous drain current @ $V_{GS} = 10V$	$T_C = 25^\circ C$	130	A
		$T_C = 100^\circ C$	86	A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ C$	390	A
$I_{DSM}$	Continuous drain current @ $V_{GS} = 10V$	$T_A = 25^\circ C$	18	A
		$T_A = 70^\circ C$	13	A
EAS	Avalanche energy, single pulsed ②	550	mJ	
$P_D$	Maximum power dissipation	$T_C = 25^\circ C$	130	W
$T_{STG}, T_J$	Storage and Junction Temperature Range		-55 to 150	$^\circ C$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.96	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	63	$^\circ C/W$



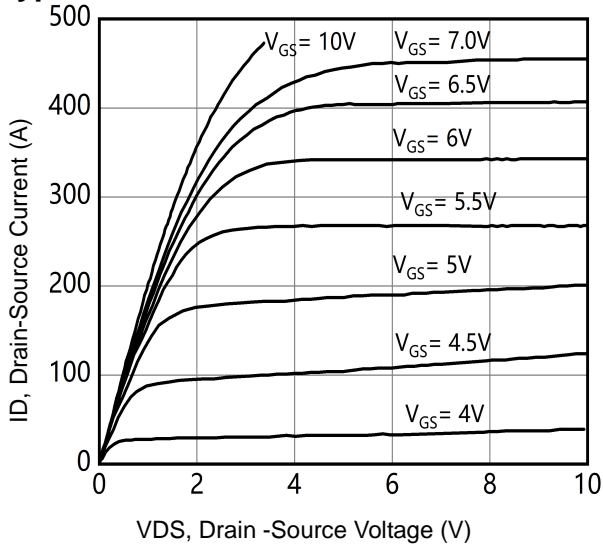
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>j</sub>=25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	80	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>j</sub> =125°C)	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
R <sub>DS(ON)</sub>	Drain-Source On- State Resistance ③	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	2.7	4.0	mΩ

<b>Dynamic Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=100kHz	--	5581	--	pF
C <sub>oss</sub>	Output Capacitance		--	1691	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	97.2	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	2	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =40V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V	--	61.4	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	20	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	8	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =40V, I <sub>D</sub> =50A, R <sub>G</sub> =2Ω, V <sub>GS</sub> =10V	--	28.5	--	ns
t <sub>r</sub>	Turn-on Rise Time		--	10.2	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	60	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	15	--	ns
<b>Source- Drain Diode Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V	--	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>sd</sub> =50A, V <sub>GS</sub> =0V di/dt=100A/μs	--	65	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	82	--	nC

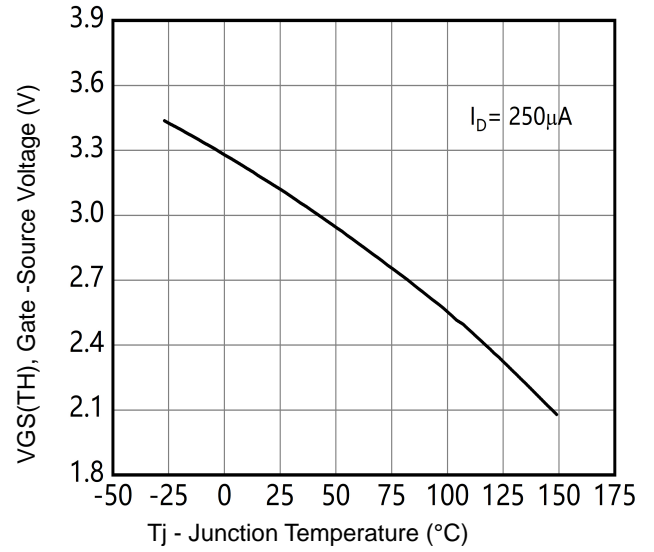
NOTE:

- ① Repetitive rating; pulse width limited by max junction temperature.
- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 10A, V<sub>GS</sub> = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

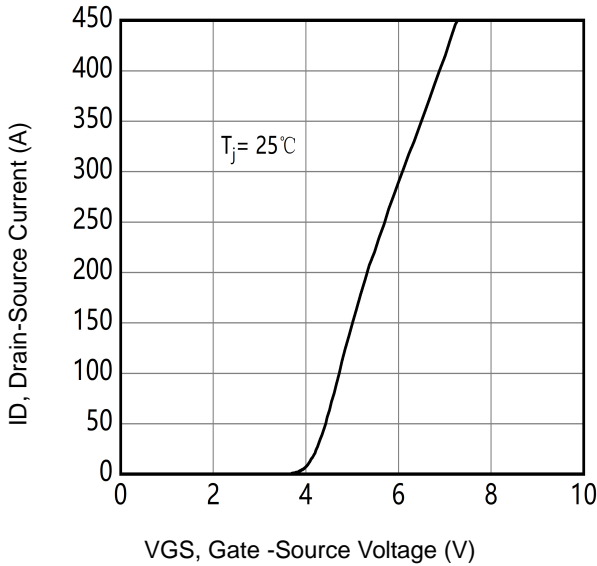
## Typical Characteristics



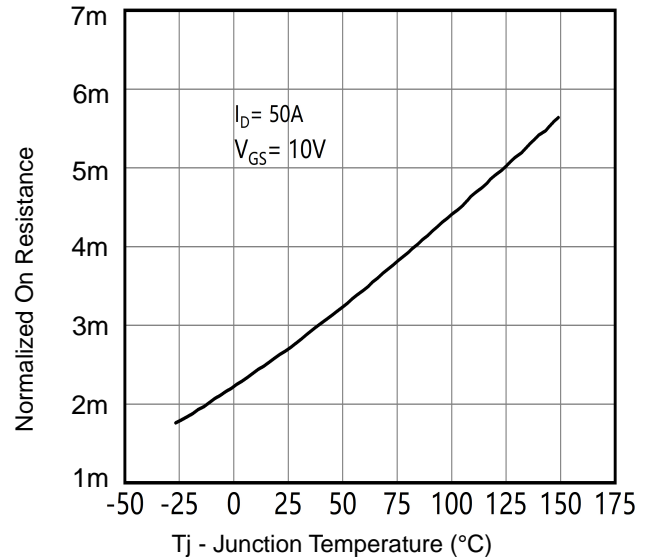
**Fig1.** Typical Output Characteristics



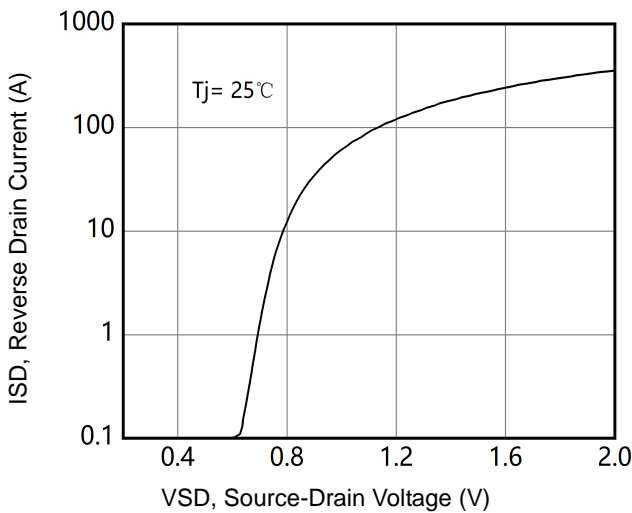
**Fig2.**  $V_{GS(TH)}$  Gate -Source Voltage Vs.  $T_j$



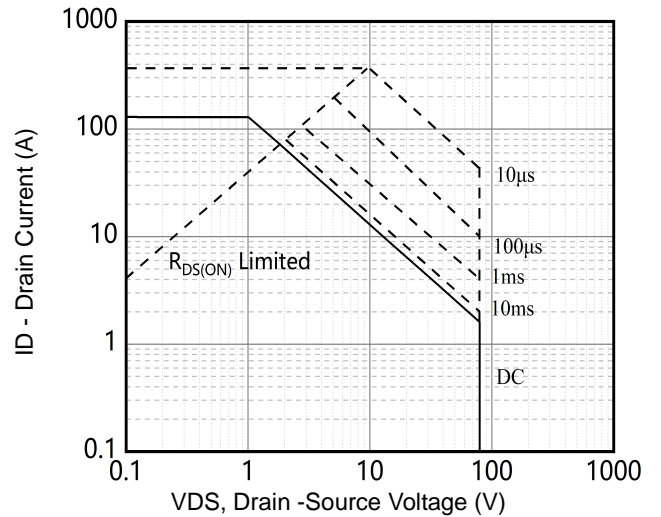
**Fig3.** Typical Transfer Characteristics



**Fig4.** Normalized On-Resistance Vs.  $T_j$

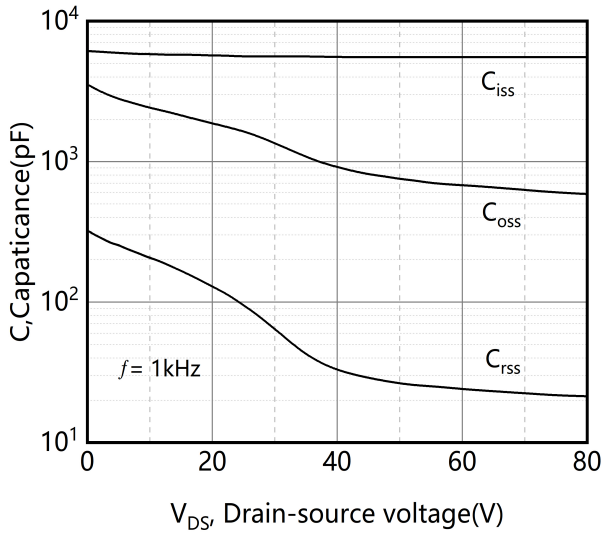


**Fig5.** Typical Source-Drain Diode Forward Voltage

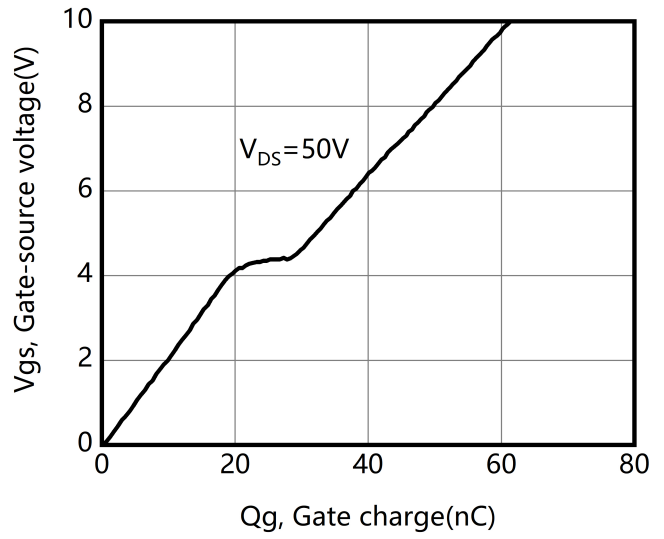


**Fig6.** Maximum Safe Operating Area

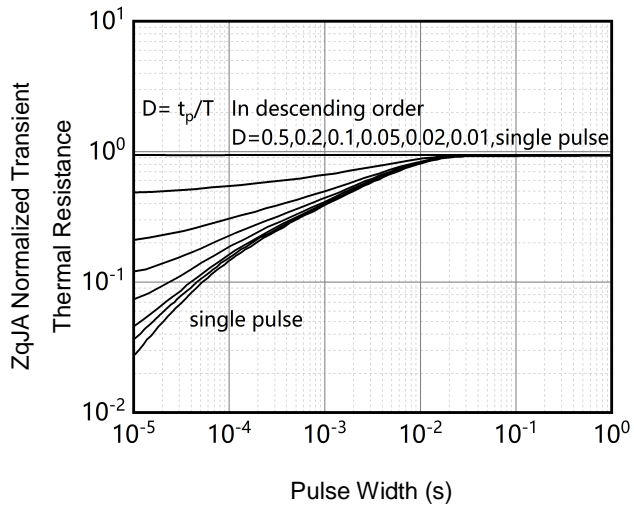
## Typical Characteristics



**Fig7.** Typical Capacitance Vs. Drain-Source Voltage

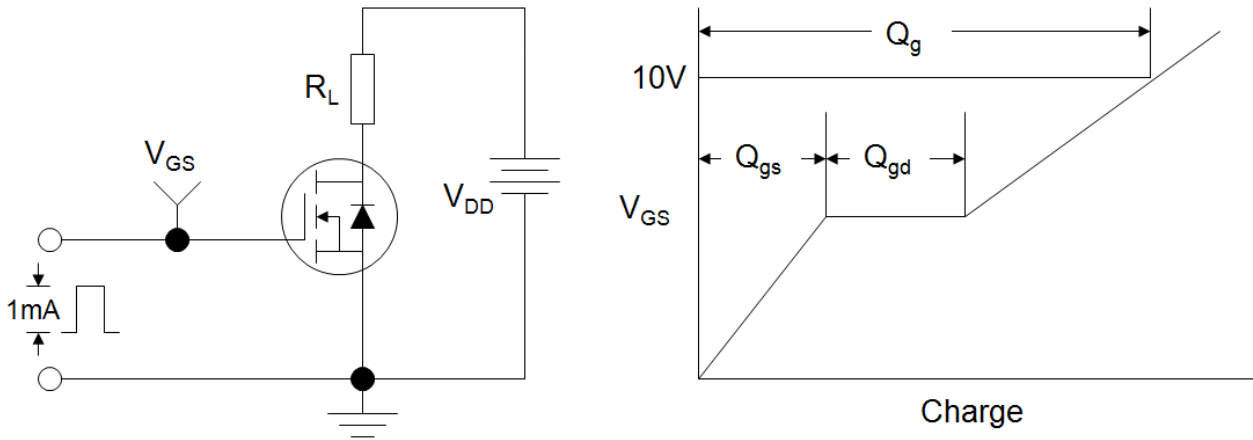


**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage

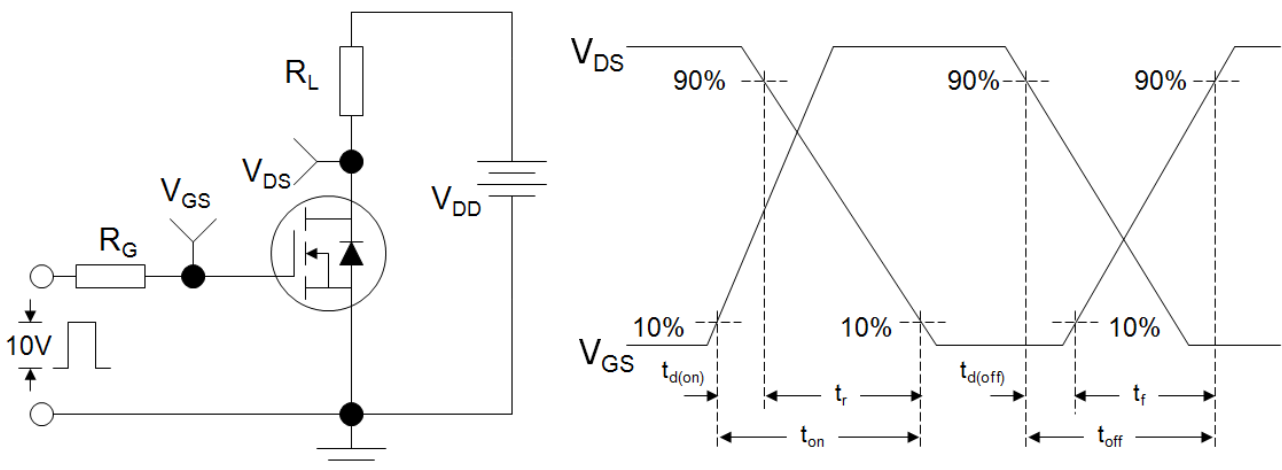


**Fig9.** Normalized Maximum Transient Thermal Impedance

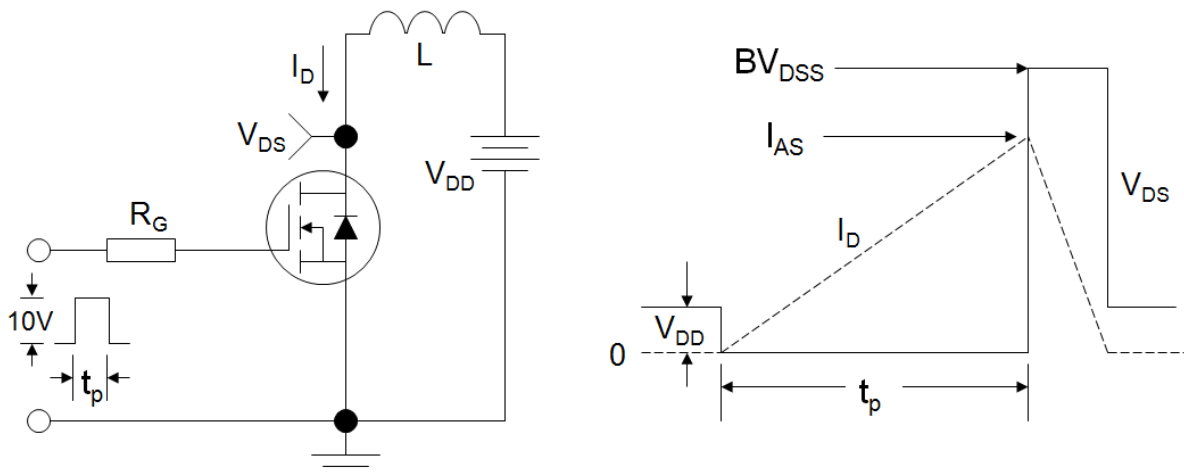
**Figure A: Gate Charge Test Circuit and Waveform**



**Figure B: Resistive Switching Test Circuit and Waveform**

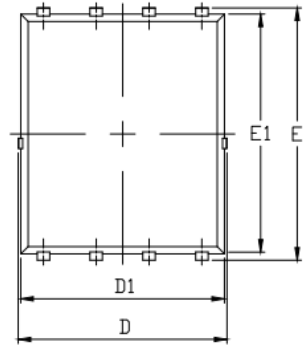


**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**

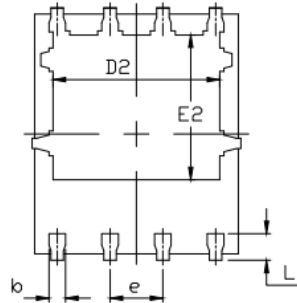


## Package Information

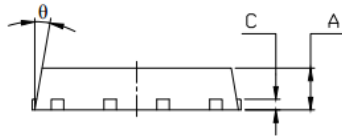
DFN5\*6 package outline dimension



Top View



Bottom View



Side View

Power56			
DIM.	MIN.	MAX.	TYP.
A	0.95	1.05	1.00
b	0.30	0.50	0.40
C	0.254		
D	5.02		
D1	4.80	5.00	4.90
D2	3.91	4.11	4.01
E	5.95	6.15	6.05
E1	5.60	5.90	5.75
E2	3.38	3.58	3.48
e	1.27REF		
L	0.45	0.65	0.55
$\theta$	10°		



## Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2022-07	Initial version